Crystalfontz America, Inc.

SPECIFICATION

| CUSTOMER: | |
|-------------|----------------|
| MODULE NO.: | CFAX12864T-TFH |

| SALES BY | APPROVED BY | CHECKED BY | PREPARED BY |
|--------------|-------------|------------|-------------|
| | | | |
| | Q | | |
| ISSUED DATE: | | | |

Crystalfontz America, Inc.

12412 East Saltese Avenue Spokane Valley, WA 99216-0357

Phone: (888) 206-9720 Fax: (509) 892-1203

Email:

techinfo@crystalfontz.com

URL: www.crystalfontz.com

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1. Module Classification Information

 $Crystal fontz\ America,\ Inc.$

| ① | Brand: CRYSTALF | ONTZ AMERICA, INCORPOR | RATED |
|-----|--------------------------------------|----------------------------------|----------------------------|
| 2 | Display Type∶ H→C | haracter Type, G→Graphic Type, | X→TAB Type |
| 3 | Display's logical dime | ensions: 128 pixels by 64 pixels | |
| 4 | Model variant: T | | |
| (5) | Backlight Type: | N→Without backlight | P→LED, Bule |
| | | B→EL, Blue green | A→LED, Amber |
| | | D→EL, Green | R→LED, Red |
| | | W→EL, White | O→LED, Orange |
| | | F→CCFL, White | G→LED, Green |
| | | Y→LED, Yellow Green | T→LED, White |
| 6 | LCD Mode: | B→TN Positive, Gray | T→FSTN Negative |
| | | N→TN Negative, | |
| | | G→STN Positive, Gray | |
| | | Y→STN Positive, Yellow Green | |
| | | M→STN Negative, Blue | |
| | | F→FSTN Positive | |
| 7 | LCD Polarizer Type/ | A→Reflective, N.T, 6:00 | H→Transflective, W.T,6:00 |
| | Temperature range/ View direction | D→Reflective, N.T, 12:00 | K→Transflective, W.T,12:00 |
| | view direction | G→Reflective, W. T, 6:00 | C→Transmissive, N.T,6:00 |
| | | J→Reflective, W. T, 12:00 | F→Transmissive, N.T,12:00 |
| | | B→Transflective, N.T,6:00 | I→Transmissive, W. T, 6:00 |
| | | E→Transflective, N.T.12:00 | L→Transmissive, W.T,12:00 |
| 8 | Special Code | CB: | |

2. Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3) Don't disassemble the LCM.
- (4) Don't operate it above the absolute maximum rating.
- (5) Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.

3.General Specification

| Item | Dimension | Unit |
|----------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------|
| Number of Characters | 128 x 64 | _ |
| Module dimension | 38.0 x44.82 x9.3(MAX) | mm |
| View area | 29.58x 17.98 | mm |
| Active area | 25.58x 15.98 | mm |
| Dot size | 0.23x 0.18 | mm |
| Dot pitch | 0.25 x 0.2 | mm |
| LCD type | FSTN Positive Transflective (In LCD production, It will occur slightly color of can only guarantee the same color in the same based on th | |
| Duty | 1/64 | , |
| View direction | 6 o'clock | |
| Backlight Type | LED, White | |

4. Absolute Maximum Ratings

| Item | Symbol | Min | Тур | Max | Unit |
|--------------------------|----------------------------------|----------|-------------|----------|------------------------|
| Operating Temperature | T_{OP} | -20 | _ | +70 | $^{\circ}\!\mathbb{C}$ |
| Storage Temperature | T_{ST} | -30 | _ | +80 | $^{\circ}\!\mathbb{C}$ |
| Input Voltage | V _I | V_{SS} | _ | V_{DD} | V |
| Supply Voltage For Logic | V _{DD} -V _{SS} | 1.8 | _ | 3.6 | V |
| Supply Voltage For LCD | Vout-V _{SS} | 6.0 | | 14.2 | V |

5. Electrical Characteristics

| Item | Symbol | Condition | Min | Тур | Max | Unit |
|------------------------|----------------------|-----------------------|---------------------|------|---------------------|------|
| Supply Voltage For | V_{DD} - V_{SS} | _ | 3.0 | 3.3 | 3.6 | V |
| Logic | 100 133 | | 3.0 | 0.0 | 3.0 | • |
| | 2 | Ta=-20°C | _ | _ | _ | V |
| Supply Voltage For LCD | V_{DD} - V_{0UT} | Ta=25°℃ | _ | 8.5 | _ | V |
| | | Ta=70°C | _ | — | _ | V |
| Input High Volt. | V_{IH} | _ | 0.8 V _{DD} | _ | V_{DD} | V |
| Input Low Volt. | V_{IL} | _ | Vss | _ | 0.2 V _{DD} | V |
| Output High Volt. | V_{OH} | _ | 0.8 V _{DD} | _ | V_{DD} | V |
| Output Low Volt. | V_{OL} | _ | Vss | | 0.2 V _{DD} | V |
| Supply Current | I_{DD} | V _{DD} =3.3V | 0.18 | 0.18 | 0.18 | mA |

6. Optical Characteristics

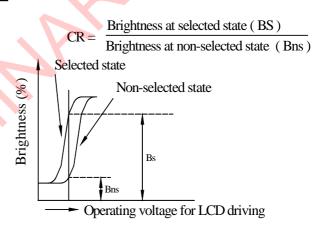
| Item | Symbol | Condition | Min | Тур | Max | Unit |
|----------------|-------------|-----------|-----|-----|-----|------|
| | $(V)\theta$ | CR≧2 | 30 | _ | 60 | deg |
| View Angle | (H) φ | CR≧2 | -45 | _ | 45 | deg |
| Contrast Ratio | CR | _ | _ | 5 | _ | _ |
| | T rise | _ | _ | 110 | 220 | ms |
| Response Time | T fall | _ | | 260 | 520 | ms |

6.1 Definitions

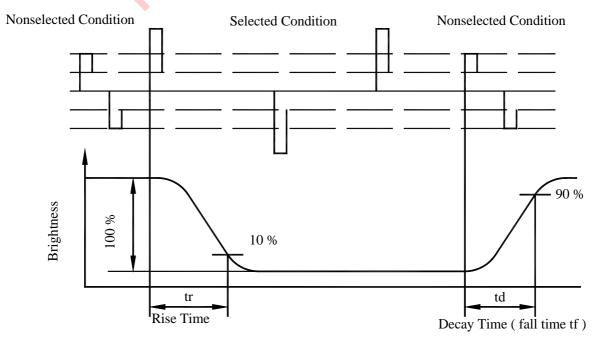
View Angles

Z (Visual angle direction) $X_{\mathfrak{S}}$

Contrast Ratio



Response Time



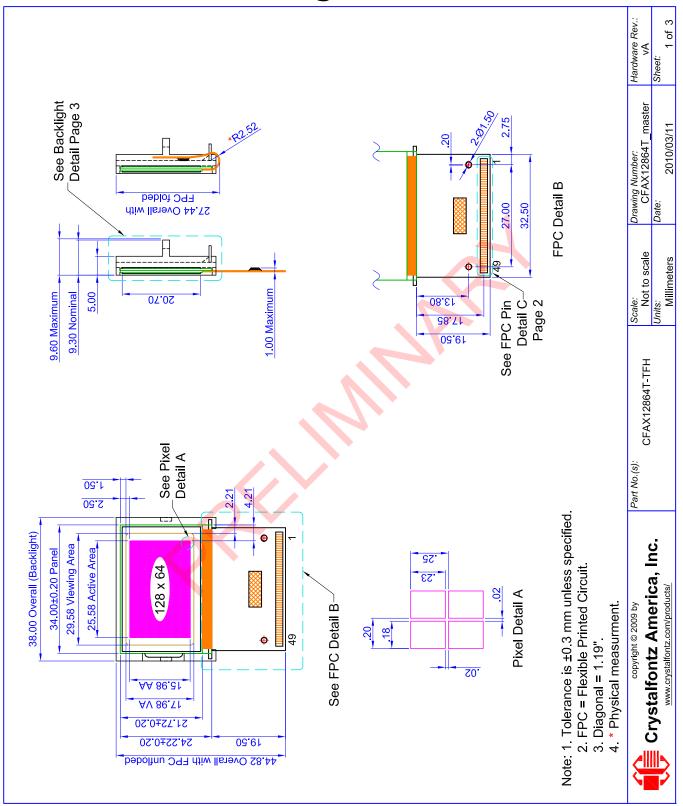
7.Interface Description

| Pin No. | Symbol | I/O | Description | | | | | |
|---------|--------|-----|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--|--|--|--|--|
| 1 | NC | | No connection | | | | | |
| 2 | IRS | I | This terminal selects the resistors for the V0 voltage level adjustment IRS = "H", Use the internal resistors IRS = "L", Do not use the internal resistors The V0 voltage level is regulated by an external resistive voltage divider attached to the VR terminal. This pad is enabled only when the master operation mode is selected. It is fixed to either "H" or "L" when the slave operation mode is selected | | | | | |
| 3 | /HPM | I | This is the power control terminal for the power supply circuit for liquid crystal drive. /HPM = "H", Normal power mode /HPM = "L", High power mode This pad is enabled only when the master operation mode is selected and it is fixed to either "H" or "L" when the slave operation mode is selected. | | | | | |
| | | | This is the parallel data input/serial data input switch terminal P/S = "H": Parallel data input P/S = "L": Serial data input The following applies depending on the P/S status: | | | | | |
| 4 | P/S | I | P/S Data/Command Data Read/Write Serial Clock | | | | | |
| 4 | F/S | 1 | "H" A0 D0 to D7 /RD, /WR - | | | | | |
| | | | "L" A0 SI (D7) Write only SCL (D6) When P/S = "L", fix D0~D5 pads to VDD or VSS level. /RD(E) and /WR (R/W) are fixed to either "H" or "L". With serial data input ,RAM | | | | | |
| | | | display data reading is not supported. | | | | | |
| 5 | C86 | I | This is the MPU interface switch terminal C86 = "H":6800 Series MPU interface C86 = "L":8080 Series MPU interface | | | | | |
| 6 | CLS | I | Terminal to select whether enable or disable the display clock internal oscillator circuit. CLS = "H": Internal oscillator circuit for display is enabled CLS = "L": Internal oscillator circuit for display is enabled (requires external input) When CLS = "L", input the display clock through the CL pad. | | | | | |
| 7 | M/S | I | This terminal selects the master/slave operation for the NT7534 chips. Master operation outputs the timing signals that required for LCD display, while slave operation inputs the timing signals required for the liquid crystal display, synchronizing the liquid crystal display system. | | | | | |
| 8 | VR | I | Voltage adjustment pad. Applies voltage between V0 and VSS using a resistive divider. | | | | | |
| 9 | V0 | I/O | LCD driver supplies voltages. The voltage determined by the LCD cell | | | | | |
| 10 | V4 | | is impedance-converted by a resistive driver or an operation amplifier | | | | | |
| 11 | V3 | | for application. Voltages should be according to the following | | | | | |

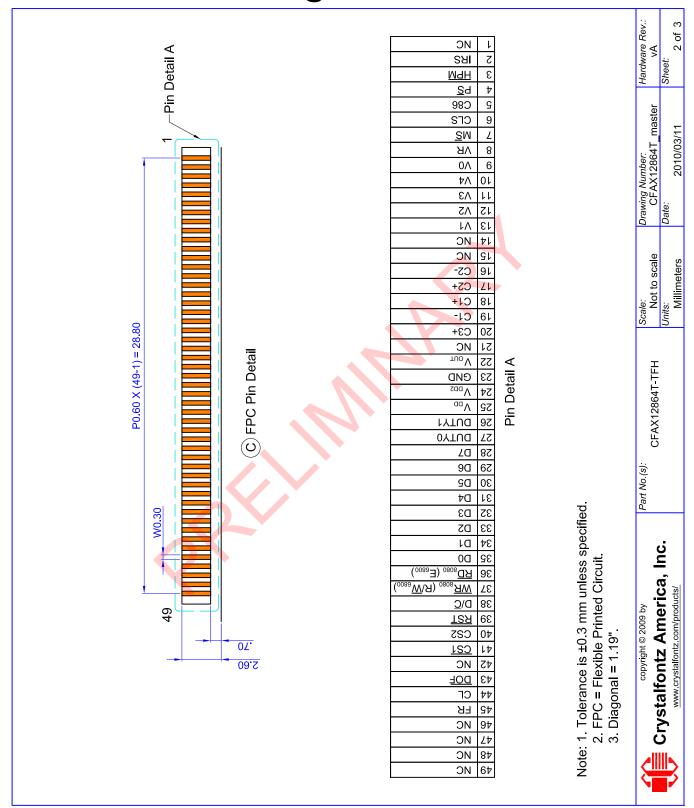
| are supplied to V1 to V4 by the on-chip power circuit. Voltages selection is performed by the LCD Bias Set command. NC No connection No connection C2- O Capacitor 2-pad for internal DC/DC voltage converter. C3+ Capacitor 1-pad for internal DC/DC voltage converter. C4+ Capacitor 1-pad for internal DC/DC voltage converter. C5+ Capacitor 1-pad for internal DC/DC voltage converter. C6+ Capacitor 1-pad for internal DC/DC voltage converter. C7- Capacitor 1-pad for internal DC/DC voltage converter. C7- Capacitor 3-pad for internal DC/DC voltage converter. No connection C7- VOUT I/O DC/DC voltage converter output | | | | PRELIMINARY |
|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|----|-------|--------|-----------------------------------------------------------------------------|
| When the on-chip operating power circuit is on ,the following voltages are supplied to V1 to V4 by the on-chip power circuit. Voltages selection is performed by the LCD Bias Set command. 14 | 12 | V2 | | relationship: |
| are supplied to V1 to V4 by the on-chip power circuit. Voltages selection is performed by the LCD Bias Set command. No connection No connection No connection Capacitor 2-pad for internal DC/DC voltage converter. Capacitor 1-pad for internal DC/DC voltage converter. Capacitor 3-pad for internal DC/DC voltage converter. No connection VOD2 VOUT VOD2 VOD2 VDD2 Supply Capacitor 3-pad for internal DC/DC voltage converter. No connection DC/DC voltage converter output Capacitor 3-pad for internal DC/DC voltage converter. No connection DC/DC voltage converter output Capacitor 3-pad for internal DC/DC voltage converter. No connection DC/DC voltage converter output Capacitor 3-pad for internal DC/DC voltage converter. No connection These are the power supply pads for the step-up voltage circuit for the LCD. These pads must be connected to each other. Power supply output for pad option Supply Capacitor 1-pad for internal DC/DC voltage converter. No connection Supply This is an 8-bit bi-directional data bus that connects to an 8-bit or 16-bit standard MPU data bus. When the serial interface is selected (P/S="L"), then D7 serves as the serial data input terminal (SD) and D6 serves as the serial clock input terminal (SCL). When the serial interface is selected, fix D0-D5 pads to VDD or VSS level. When the chip select is inactive, D0 to D7 are set to high impedance. | | | | $V_0 \geqslant V_1 \geqslant V_2 \geqslant V_3 \geqslant V_4 \geqslant V_5$ |
| Voltages selection is performed by the LCD Bias Set command. No connection No connection No connection C2- O Capacitor 2-pad for internal DC/DC voltage converter. C2+ O Capacitor 1-pad for internal DC/DC voltage converter. C3+ Capacitor 1-pad for internal DC/DC voltage converter. C3+ Capacitor 1-pad for internal DC/DC voltage converter. C3+ Capacitor 3+pad for internal DC/DC voltage converter. No connection C3+ VOUT NO DC/DC voltage converter output C3+ VSS O Ground output for pad option. C4+ VDD2 Supply C5- VDD O Power supply output for pad option C6- DUTY1 C7- DUTY0 C8+ DUTY1 C9- DC- Voltage converter output for pad option C9- DUTY1 C9- DUTY1 This is an 8-bit bi-directional data bus that connects to an 8-bit or 16-bit standard MPU data bus. When the serial interface is selected (P/S= "L"), then D7 serves as the serial data input terminal (SCL). When the serial interface is selected, fix D0-D5 pads to VDD or VSS level. When the chip select is inactive, D0 to D7 are set to high impedance. | | | | When the on-chip operating power circuit is on ,the following voltages |
| 14 NC No connection 15 NC No connection 16 C2- O Capacitor 2-pad for internal DC/DC voltage converter. 17 C2+ O Capacitor 2+pad for internal DC/DC voltage converter. 18 C1+ Capacitor 1+pad for internal DC/DC voltage converter. 19 C1- Capacitor 1-pad for internal DC/DC voltage converter. 20 C3+ Capacitor 3+pad for internal DC/DC voltage converter. 21 NC No connection 22 VOUT I/O DC/DC voltage converter output 23 VSS O Ground output for pad option. 24 VDD2 Supply These are the power supply pads for the step-up voltage circuit for the LCD. These pads must be connected to each other. 25 VDD O Power supply output for pad option 26 DUTY1 I Select the maximum LCD driver duty 27 DUTY0 I Select the maximum LCD driver duty 28 D7 I/O This is an 8-bit bi-directional data bus that connects to an 8-bit or 16-bit standard MPU data bus. When the serial interface is selected (P/S= "L"), then D7 serves as the serial data input terminal (SI) and D6 serves as the serial clock input terminal (SCL). When the serial interface is selected, fix D0-D5 pads to VDD or VSS level. When the chip select is inactive, D0 to D7 are set to high impedance. | 13 | V1 | | are supplied to V1 to V4 by the on-chip power circuit. |
| No connection | | | | Voltages selection is performed by the LCD Bias Set command. |
| No connection | | | | |
| Capacitor 2-pad for internal DC/DC voltage converter. | 14 | NC | | No connection |
| 17 C2+ O Capacitor 2+pad for internal DC/DC voltage converter. 18 C1+ Capacitor 1+pad for internal DC/DC voltage converter. 19 C1- Capacitor 1-pad for internal DC/DC voltage converter. 20 C3+ Capacitor 3+pad for internal DC/DC voltage converter. 21 NC No connection 22 VOUT I/O DC/DC voltage converter output 23 VSS O Ground output for pad option. 24 VDD2 Supply These are the power supply pads for the step-up voltage circuit for the LCD. These pads must be connected to each other. 25 VDD O Power supply output for pad option 26 DUTY1 27 DUTY0 28 D7 I/O This is an 8-bit bi-directional data bus that connects to an 8-bit or 16-bit standard MPU data bus. When the serial interface is selected (P/S= "L"), then D7 serves as the serial data input terminal (SCL). When the serial interface is selected, fix D0~D5 pads to VDD or VSS level. When the chip select is inactive, D0 to D7 are set to high impedance. | 15 | NC | | No connection |
| Capacitor 1+pad for internal DC/DC voltage converter. Capacitor 1-pad for internal DC/DC voltage converter. Capacitor 3+pad for internal DC/DC voltage converter. Capacitor 3+pad for internal DC/DC voltage converter. No connection VOUT Capacitor 3+pad for internal DC/DC voltage converter. No connection Capacitor 3+pad for internal DC/DC voltage converter. No connection DC/DC voltage converter output Supply Capacitor 3+pad for internal DC/DC voltage converter. No connection Capacitor 3+pad for internal DC/DC voltage converter. No connection Capacitor 3+pad for internal DC/DC voltage converter. No connection These are the power supply pads for the step-up voltage circuit for the LCD. These pads must be connected to each other. Power supply output for pad option Select the maximum LCD driver duty This is an 8-bit bi-directional data bus that connects to an 8-bit or 16-bit standard MPU data bus. When the serial interface is selected (P/S= "L"), then D7 serves as the serial data input terminal (SI) and D6 serves as the serial clock input terminal (SCL). When the serial interface is selected, fix D0~D5 pads to VDD or VSS level. When the chip select is inactive, D0 to D7 are set to high impedance. | 16 | C2- | О | Capacitor 2-pad for internal DC/DC voltage converter. |
| Capacitor 1-pad for internal DC/DC voltage converter. Capacitor 1-pad for internal DC/DC voltage converter. Capacitor 3-pad for internal DC/DC voltage converter. Capacitor 3-pad for internal DC/DC voltage converter. No connection DC/DC voltage converter output VSS OGround output for pad option. These are the power supply pads for the step-up voltage circuit for the LCD. These pads must be connected to each other. Power supply output for pad option CED These pads must be connected to each other. Power supply output for pad option Select the maximum LCD driver duty This is an 8-bit bi-directional data bus that connects to an 8-bit or 16-bit standard MPU data bus. When the serial interface is selected (P/S= "L"), then D7 serves as the serial data input terminal (SI) and D6 serves as the serial clock input terminal (SCL). When the serial interface is selected, fix D0-D5 pads to VDD or VSS level. When the chip select is inactive, D0 to D7 are set to high impedance. | 17 | C2+ | О | Capacitor 2+pad for internal DC/DC voltage converter. |
| Capacitor 1-pad for internal DC/DC voltage converter. Capacitor 3+pad for internal DC/DC voltage converter. No connection VOUT I/O DC/DC voltage converter output VSS O Ground output for pad option. These are the power supply pads for the step-up voltage circuit for the LCD. These pads must be connected to each other. VDD O Power supply output for pad option CD DUTY1 CO DUTY1 This is an 8-bit bi-directional data bus that connects to an 8-bit or 16-bit standard MPU data bus. When the serial interface is selected (P/S= "L"), then D7 serves as the serial data input terminal (SI) and D6 serves as the serial clock input terminal (SCL). When the serial interface is selected interface is selected interface is selected. When the chip select is inactive, D0 to D7 are set to high impedance. | 18 | C1+ | | Capacitor 1+pad for internal DC/DC voltage converter. |
| Capacitor 3+pad for internal DC/DC voltage converter. | 19 | C1- | | Capacitor 1-pad for internal DC/DC voltage converter. |
| No connection 22 | 20 | C3+ | | Capacitor 3+pad for internal DC/DC voltage converter. |
| VSS OGround output for pad option. These are the power supply pads for the step-up voltage circuit for the LCD. These pads must be connected to each other. DUTY1 DUTY0 Select the maximum LCD driver duty This is an 8-bit bi-directional data bus that connects to an 8-bit or 16-bit standard MPU data bus. When the serial interface is selected (P/S= "L"), then D7 serves as the serial data input terminal (SI) and D6 serves as the serial clock input terminal (SCL). When the serial interface is selected, fix D0~D5 pads to VDD or VSS level. When the chip select is inactive, D0 to D7 are set to high impedance. | 21 | NC | | No connection |
| These are the power supply pads for the step-up voltage circuit for the LCD. These pads must be connected to each other. VDD O Power supply output for pad option I Select the maximum LCD driver duty DUTY0 Below the maximum LCD driver duty I Select the maximum LCD driver duty I Select the maximum LCD driver duty I This is an 8-bit bi-directional data bus that connects to an 8-bit or 16-bit standard MPU data bus. When the serial interface is selected (P/S= "L"), then D7 serves as the serial data input terminal (SI) and D6 serves as the serial clock input terminal (SCL). When the serial interface is selected, fix D0~D5 pads to VDD or VSS level. When the chip select is inactive, D0 to D7 are set to high impedance. | 22 | VOUT | I/O | DC/DC voltage converter output |
| Supply LCD. These pads must be connected to each other. Power supply output for pad option I Select the maximum LCD driver duty DUTY0 Below the maximum LCD driver duty I Select the maximum LCD driver duty I Select the maximum LCD driver duty I This is an 8-bit bi-directional data bus that connects to an 8-bit or 16-bit standard MPU data bus. When the serial interface is selected (P/S= "L"), then D7 serves as the serial data input terminal (SI) and D6 serves as the serial clock input terminal (SCL). When the serial interface is selected, fix D0~D5 pads to VDD or VSS level. When the chip select is inactive, D0 to D7 are set to high impedance. | 23 | VSS | 0 | Ground output for pad option. |
| Supply LCD. These pads must be connected to each other. 25 | 24 | VDD2 | ~ | These are the power supply pads for the step-up voltage circuit for the |
| 25 VDD O Power supply output for pad option 26 DUTY1 27 DUTY0 28 D7 29 D6 30 D5 31 D4 32 D3 33 D2 Power supply output for pad option Select the maximum LCD driver duty This is an 8-bit bi-directional data bus that connects to an 8-bit or 16-bit standard MPU data bus. When the serial interface is selected (P/S= "L"), then D7 serves as the serial data input terminal (SI) and D6 serves as the serial clock input terminal (SCL). When the serial interface is selected, fix D0~D5 pads to VDD or VSS level. When the chip select is inactive, D0 to D7 are set to high impedance. | | .232 | Supply | LCD. These pads must be connected to each other. |
| I Select the maximum LCD driver duty 28 D7 D07 D08 D09 D09 D09 D09 D09 D09 D09 | 25 | VDD | О | |
| DUTY0 28 D7 1/O This is an 8-bit bi-directional data bus that connects to an 8-bit or 16-bit standard MPU data bus. When the serial interface is selected (P/S= "L"), then D7 serves as the serial data input terminal (SI) and D6 serves as the serial clock input terminal (SCL). When the serial interface is selected, fix D0~D5 pads to VDD or VSS level. When the chip select is inactive, D0 to D7 are set to high impedance. | 26 | DUTY1 | - | |
| 29 D6 30 D5 31 D4 32 D3 33 D2 16-bit standard MPU data bus. When the serial interface is selected (P/S= "L"), then D7 serves as the serial data input terminal (SI) and D6 serves as the serial clock input terminal (SCL). When the serial interface is selected, fix D0~D5 pads to VDD or VSS level. When the chip select is inactive, D0 to D7 are set to high impedance. | 27 | DUTY0 | I | Select the maximum LCD driver duty |
| When the serial interface is selected (P/S= "L"), then D7 serves as the serial data input terminal (SI) and D6 serves as the serial clock input terminal (SCL). When the serial interface is selected, fix D0~D5 pads to VDD or VSS level. When the chip select is inactive, D0 to D7 are set to high impedance. When the chip select is inactive, D0 to D7 are set to high impedance. | 28 | D7 | I/O | |
| terminal (SCL). When the serial interface is selected, fix D0~D5 pads to VDD or VSS level. When the chip select is inactive, D0 to D7 are set to high impedance. | 29 | D6 | | |
| 31 D4 to VDD or VSS level. 32 D3 When the chip select is inactive, D0 to D7 are set to high impedance. 33 D2 | 30 | D5 | | serial data input terminal (SI) and D6 serves as the serial clock input |
| 32 D3 33 D2 | 31 | D4 | | to VDD or VSS level. |
| | 32 | D3 | | When the chip select is inactive, D0 to D7 are set to high impedance. |
| 34 D1 | 33 | D2 | | |
| | 34 | D1 | | |

| | | | IKELIMINAKI |
|----|------|-----|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 35 | D0 | | |
| 36 | /RD | I | When connected to an 8080 MPU, it is active LOW. This pad is connected to the /RD signal of the 8080 MPU, and the NT7534 data bus is in an output status when this signal is "L". When connected to a 6800 Series MPU, this is active HIGH. This is used as an enable clock input of the 6800 series MPU |
| 37 | /WR | I | When connected to an 8080 MPU, this is active LOW. This terminal connects to the 8080 MPU, and the NT7534 data bus are latched at rising edge of the /WR signal. When connected to an 8080 MPU, this is the read/write control signal input terminal. When R/W= "H": Read When R/W= "L": Write |
| 38 | A0 | I | This is connected to the least significant bit of the normal MPU address bus, and it determines whether the data bits are data or a command. A0="H": Indicate that D0 to D7 are display data A0="L": Indicate that D0 to D7 are control data |
| 39 | /RES | I | When /RES is set to "L" the settings are initialized. The reset operation is performed by the /RES signal level. |
| 40 | CS2 | I | This is the chip select signal |
| 41 | /CS1 | | This is the chip select signal |
| 42 | NC | | No connection |
| 43 | /DOF | I/O | This is the liquid crystal display blanking control terminal. M/S="H":output M/S= "L":Inptu When the NT7534chip is used in master/slave mode, the various DOF terminals must be connected. |
| 44 | CL | | This is the display clock input terminal .When the NT7534 chips are used in master/slave mode ,the various CL terminals must be connected. |
| 45 | FR | I/O | This is the liquid crystal alternating current signal I/O terminal M/S="H":output M/S= "L":Inptut When the NT7534chip is used in master/slave mode, the various FR terminals must be connected. |
| 46 | NC | | No connection |
| 47 | NC | | No connection |
| 48 | NC | | No connection |
| 49 | NC | | No connection |

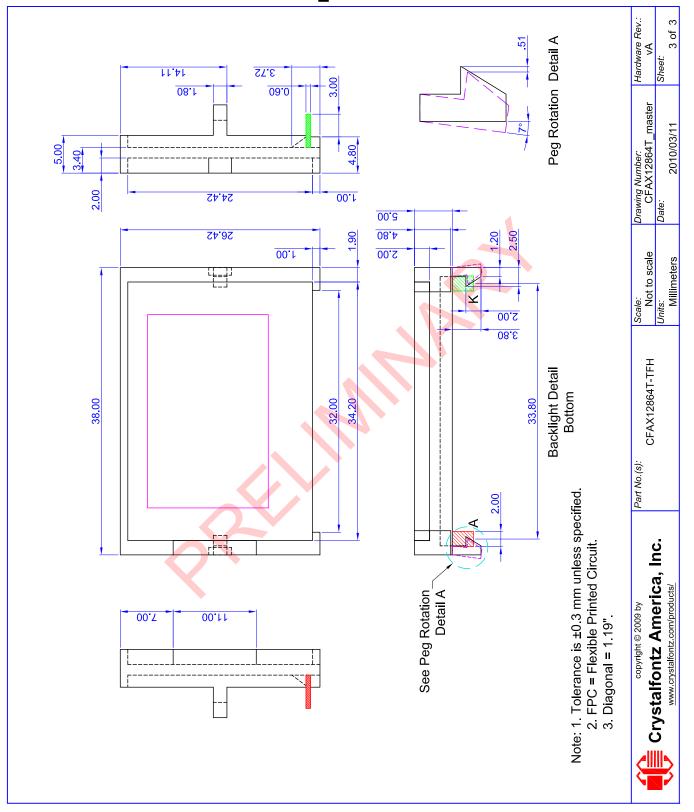
8. Contour Drawing



8.Contour Drawing 7cbH"



8.Contour Drawib['7cbH""



9. Fuction Description

Refer to IC NT7534 data sheet



10.RELIABILITY

Crystalfontz America, Inc.

Content of Reliability Test (wide temperature, -20°c~70°C)

| | Environmental Test | | | | | | |
|-----------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|----------------------------------------------------------------------------------------------------------------------------|------|--|--|--|--|
| Test Item | Content of Test | Test Condition | Note | | | | |
| High Temperature storage | Endurance test applying the high storage temperature for a long time. | 80°C 200hrs | 2 | | | | |
| Low Temperature storage | Endurance test applying the high storage temperature for a long time. | -30℃ 200hrs | 1,2 | | | | |
| High Temperature Operation | Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time. | 70°C 200hrs | | | | | |
| Low Temperature Operation | Endurance test applying the electric stress under low temperature for a long time. | -20°ℂ 200hrs | 1 | | | | |
| High Temperature/ Humidity Operation | The module should be allowed to stand at 60 °C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature. | 60°C,90%RH 96hrs | 1,2 | | | | |
| Thermal shock resistance | The sample should be allowed stand the following 10 cycles of operation -20°C 25°C 70°C 30min 5min 30min 1 cycle | -20°C/70°C 10 cycles | | | | | |
| Vibration test | Endurance test applying the vibration during transportation and using. | Total fixed amplitude: 15mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes | | | | | |
| Static electricity test | Endurance test applying the electric stress to the terminal. | VS=800V,RS=1.5kΩ CS=100pF 1 time | | | | | |

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: Vibration test will be conducted to the product itself without putting it in a container.

11. Backlight Information

Specification

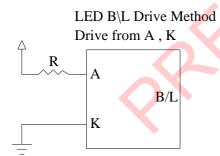
Crystalfontz America, Inc. 12412 East Saltese Avenue

Spokane Valley, WA 99216

| speemeanon | | 1 | ı | | | T |
|------------------------------------------|--------|------|-----|-----|-------------------|-----------------------------------------|
| PARAMETER | SYMBOL | MIN | TYP | MAX | UNIT | TEST CONDITION |
| Supply Current | ILED | 28.8 | 32 | 50 | mA | V= 3.5V |
| Supply Voltage | V | 3.4 | 3.5 | 3.6 | V | _ |
| Reverse Voltage | VR | | | 5 | V | - |
| Luminous Intensity | IV | 65 | 100 | | CD/M ² | ILED=32mA |
| LED Life Time (For Reference only) | _ | _ | 10K | _ | Hr. | ILED=32mA 25°C,50-60%RH, (Note 1) |
| Color | White | | • | | X | |

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Note1: 10K hours is only an estimate for reference.



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PRELIMINARY

12. Inspection specification

| NO | Item | Criterion | | | | AQL | |
|----|-----------------------------------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------|------------------------------------------------------------------------------------------|------|-----------------------------------------|------|
| 01 | Electrical Testing | 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. | | | | | 0.65 |
| 02 | Black or white spots on LCD (display only) | 2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm | | | | | 2.5 |
| 03 | LCD black spots, white spots, contamination (non-display) | 3.1 Round type: $\Phi = (x + y) / X$ | | ving drawing SIZE $\Phi \leq 0$ $0.10 < \Phi \leq 0$ $0.20 < \Phi \leq 0$ $0.25 < \Phi$ |).20 | Acceptable Q TY Accept no dense 2 1 0 | 2.5 |
| | | 3.2 Line type : (A | | | | | |
| | | * | Length | Width | | Acceptable Q TY | |
| | | | L≦3.0 | $\begin{array}{c c} & W \leq 0.02 \\ \hline & 0.02 < W \leq 0.03 \end{array}$ | 3 | Accept no dense | 2.5 |
| | | | L≦2.5 | $0.03 < W \le 0.05$ | 5 | 2 | |
| | | | | 0.05 < W | | As round type | |
| 04 | Polarizer bubbles | If bubbles are visible, judge using black spot specifications, no easy to find, mus check in specify direction. | 0.50 1.00 | Size Φ $\Phi \le 0.20$ $\Phi \le 0.50$ $\Phi \le 1.00$ Φ Total Q TY | 1 | acceptable Q TY accept no dense 3 2 0 3 | 2.5 |

| NO | Item | Criterion | | | | |
|-----|---------------|---------------------------------------------------------------------|--------------------------------|--------------------------|-----|--|
| 05 | Scratches | Follow NO.3 LCD black spots, white spots, contamination | | | | |
| | | | : Glass thickness a: LCD h: | thickness side length | | |
| | | 6.1.1 Chip on panel surface and crack between panels: | | | | |
| | | × × | | 2 | | |
| | | | 72 | 1 | | |
| | | | 0 | | | |
| | Chipped glass | z: Chip thickness | y: Chip width | x: Chip length | | |
| 0.5 | | Z≦1/2t | Not over viewing area | x≤1/8a | 2.5 | |
| 06 | | $1/2t < z \le 2t$ | Not exceed 1/3k | x≤1/8a | 2.5 | |
| | | \odot If there are 2 or more | chips, x is total length of ea | ach chip. | | |
| | | 6.1.2 Corner crack: | | | | |
| | | o.1.2 Comor crack. | (-) | | | |
| | | | X X X | | | |
| | | | 7 | | | |
| | | | | | | |
| | | | 90 30 39 | | | |
| | | z: Chip thickness | y: Chip width | x: Chip length | | |
| | | Z≦1/2t | Not over viewing area | x ≤ 1/8a | | |
| | | $1/2t < z \le 2t$ | Not exceed 1/3k | x ≤ 1/8a | | |
| | | ⊙ If there are 2 or more chips, x is the total length of each chip. | | | | |
| | | | | | | |

| NO | Item | Criterion | | | | |
|----|-------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----|--|--|--|
| 06 | Glass | $\begin{array}{c ccccccccccccccccccccccccccccccccccc$ | 2.5 | | | |
| | | y: Chip width x: Chip length z: Chip thickness $y \le L$ $x \le 1/8a$ $0 < z \le t$ ① If the chipped area touches the ITO terminal, over $2/3$ of the ITO must remain and be inspected according to electrode terminal specifications. ③ If the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. $y: width$ $x: length$ $y \le 1/3L$ $x \le a$ | | | | |

| NO | Item | Criterion | | |
|----|-----------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------------------------|--|
| 07 | Cracked glass | The LCD with extensive crack is not acceptable. | 2.5 | |
| 08 | Backlight elements | 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. | 0.65 2.5 0.65 | |
| 09 | Bezel | 9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications. | 2.5 0.65 | |
| 10 | PCB · COB | 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB | | |
| 11 | Soldering | 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. | 2.5 2.5 2.5 0.65 | |

| NO | Item | Criterion | AQL |
|----|-----------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------------------------|
| 12 | General appearance | 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it causes the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 LCD pin loose or missing pins. 12.10 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to product specification sheet. | 2.5 0.65 2.5 2.5 2.5 2.5 0.65 0.65 0.65 |

13. Material List of Components for RoHS

 Crystalfontz America, Inc. hereby declares that all of or part of products, including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

| Material | (Cd) | (Pb) | (Hg) | (Cr6+) | PBBs | PBDEs |
|--------------------------------------------------|------------|-------------|-------------|-------------|-------------|-------------|
| Limited Value | 100 ppm | 1000 ppm | 1000 ppm | 1000 ppm | 1000 ppm | 1000 ppm |
| Above limited value is set up according to RoHS. | | | | | | |

- 2. Process for RoHS requirement:
 - (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
 - (2) Heat-resistance temp. :

Reflow: 250°C,30 seconds Max.;

Connector soldering wave or hand soldering : 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°C;

Recommended customer's soldering temp. of connector : 280°C, 3 seconds.